



Material Content Data Sheet



Sales Product Name		IKD10N60R		Issued		20. July 2018		
MA#		MA000966876						
Package		PG-TO252-3-313		Weight*		317.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.407	0.44	0.44	4431	4431
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		464	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.34	46.40	463403	464006
wire	non noble metal	aluminium	7429-90-5	0.922	0.29	0.29	2906	2906
encapsulation	organic material	carbon black	1333-86-4	1.419	0.45		4470	
	plastics	epoxy resin	-	24.831	7.82		78227	
	inorganic material	silicondioxide	60676-86-0	115.643	36.43	44.70	364313	447010
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11782	11782
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4475	4486
solder	noble metal	silver	7440-22-4	0.039	0.01		122	
	non noble metal	tin	7440-31-5	0.031	0.01		98	
	non noble metal	lead	7439-92-1	1.481	0.47	0.49	4666	4886
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60415	60493
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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